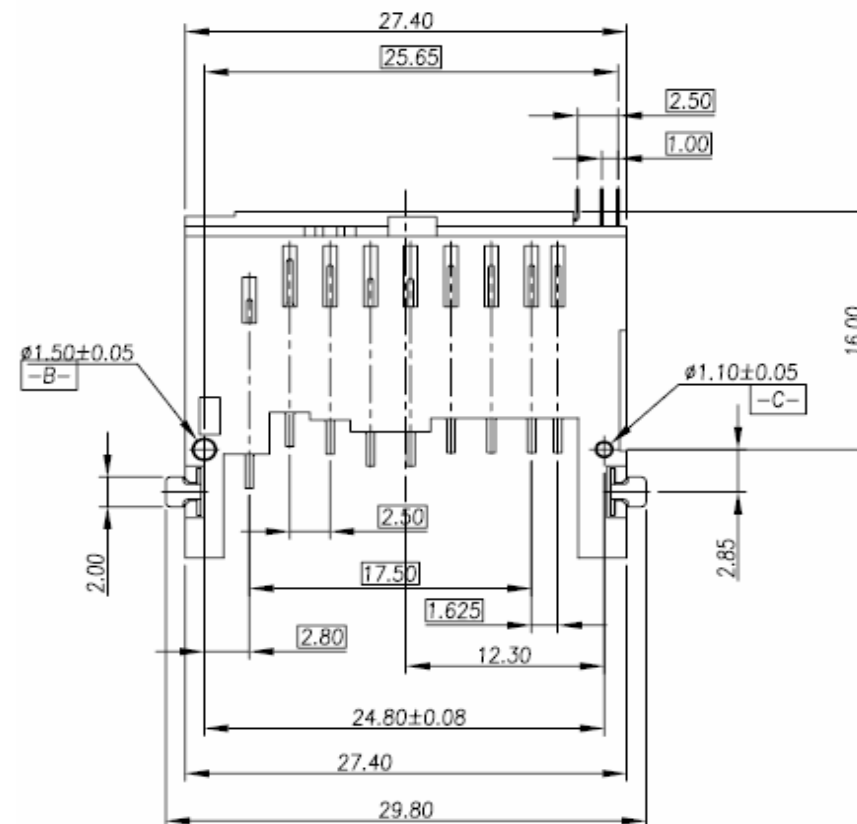


EDCON-COMPONENTS



Technical Discription

Insulator:	Thermal Plastic UL94V-0
Contacts:	Copper Alloy
Boardlock:	Copper Alloy
Contact Plating Area:	3μ AU or Select. 1μ AU Select.
Solder Tails Area:	100μ Tin/Lead Free Mate Tin
Contact Number:	9Pin
Electrical	
Curent Rating:	1A max.
Contact Resistacne::	100mΩ max.
Insuation Resistance:	1000MΩ Min 500VDC
Mechanical:	
Lifetime:	10000 Cycles.
Temperature Range:	- 25°C to +85°C



1	CD/DAT3
2	CMD/DI
3	VSS1
4	VDD
5	CLK/SCLK
6	VSS2
7	DAT0
8	DAT1
9	DAT2

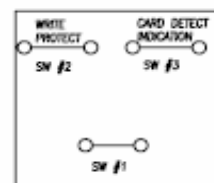
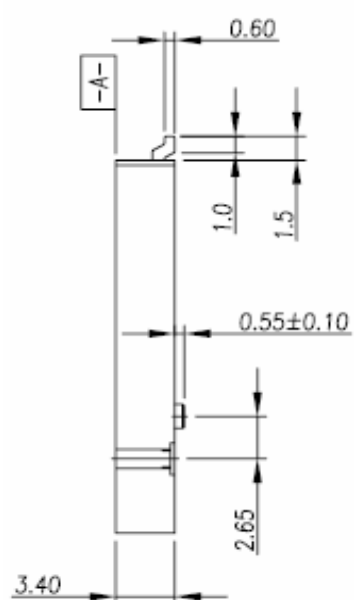
TOP Mount

SD-CARD Connector

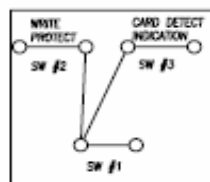
Part No.: T58007

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.11.2010	Customer:
APPD:	Schumi			FINISH	Jamy		Sheet No.	1 from 5		

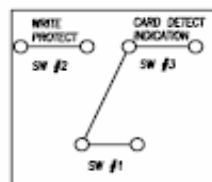
EDCON-COMPONENTS



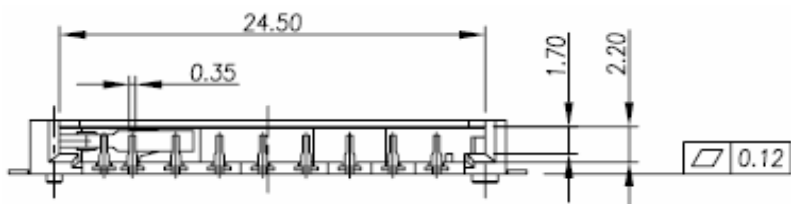
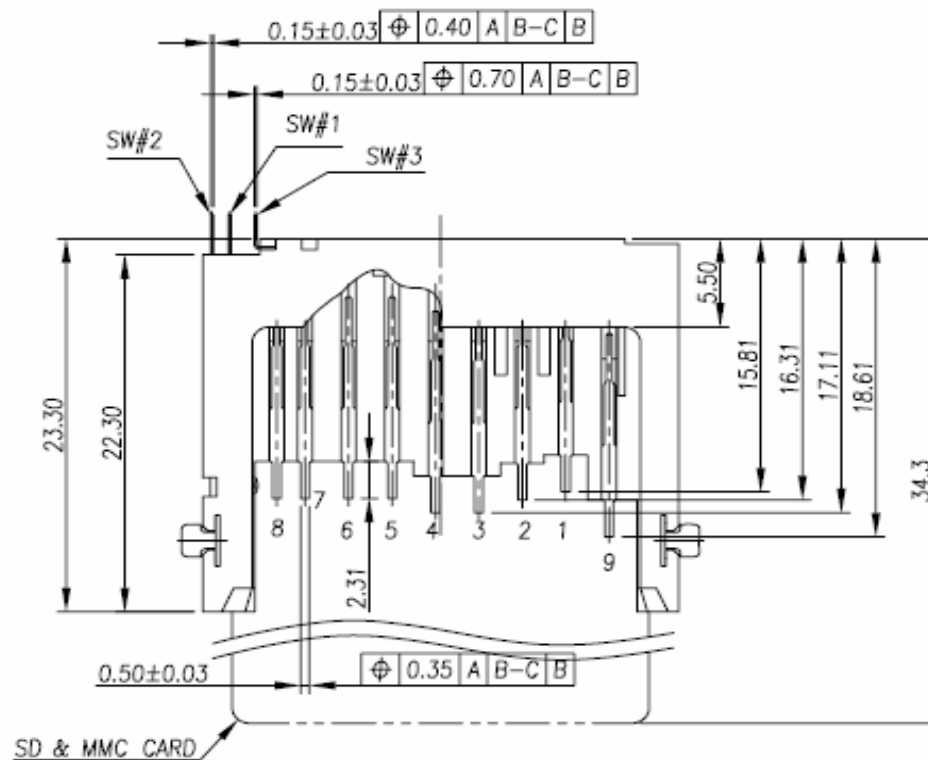
WITHOUT CARD



CARD INSERTED
WRITE PROTECT : UNLOCK



CARD INSERTED
WRITE PROTECT : LOCK



SD-CARD Connector

Part No.: **T58007**

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.11.2010
APPD:	Schumi			FINISH	Jamy		Sheet No.	2 from 5	Customer:

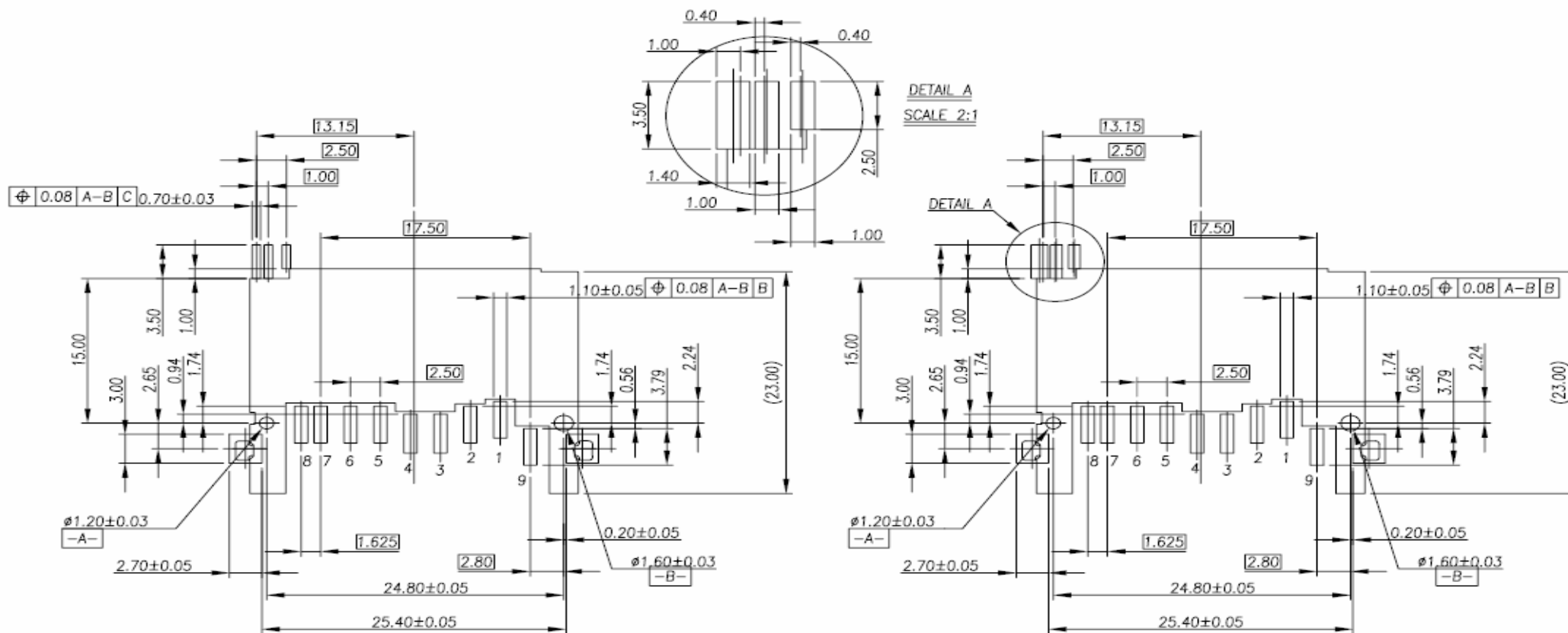
www.edcon-components.com

email: info@edcon-components.com

EDCON-COMPONENTS



PCB Layout



SD-CARD Connector

Part No.: **T58007**

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.11.2010
APPD:	Schumi			FINISH	Jamy		Sheet No.	3 from 5	Customer:

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email: info@edcon-components.com



Ordering Informations

Serie	Contact Plating	ROHS	Packing							
T58007	A	R	TY							

A = 10µ Gold Plating	R = ROHS Conform	TY = Tray Packing
B = 3µ Gold Plating	N = Non ROHS Conform	

SD-CARD Connector
Part No.: T58007
Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.11.2010
APPD:	Schumi			FINISH	Jamy		Sheet No.		4 from 5



Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



SD-CARD Connector	
Part No.:	T58007
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.11.2010
APPD:	Schumi			FINISH	Jamy		Sheet No.	5 from 6	